

ABSTRACT OF THE DISCLOSURE

5 A semiconductor device according to one embodiment
includes a substrate, a semiconductor chip arranged
on the substrate, a first electrode formed in the
substrate and connected to the semiconductor chip,
a concave portion provided on a side of the substrate,
the concave portion being formed to a depth not to
reach a top of the substrate from a back of the
substrate, and at least part of the first electrode
10 being exposed to the concave portion, and a metal layer
formed on the at least part of the first electrode.

202320-0325001
1080580-022502